



Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information		*: Required Field

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2024-10-28
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	MDG CHAMPION	Representative title	MDGMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty statement

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Legal statement

Supplier acceptance*	true	Legal declaration*	Standard
Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.			



Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
STM32WBA65RIV7	60GB*4B0XXXZ	A	998Z	2024-10-28
Amount	Unit of measure	Unit type	ST ECOPACK grade	
184	mg	Each	ECOPACK® 3	

Manufacturing information				
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles		
3	260	3		
Bulk solder termination	Terminal plating	Terminal base alloy	Comment	
Not Applicable	Tin (Sn), matte	Copper Alloy	0	
Package designator	Package size	Number of instances	Shape	
QFN	8x8	68	Flat	
Comment	Package : B029 VFQFPN 8X8X1.0 68L PITCH 0.4 DM00319327			

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015		Response
1 - Product(s) meets EU RoHS requirement without any exemptions		true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		false
Exemption Id.	Description	
,		

QueryList : REACH-27th June 2024				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
,	#N/A			



Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	60GB*4B0XXXZ		183.7154		6000000.0	1000000.0
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	7.842	mg	supplier	die	Silicon (Si)	7440-21-3		7.412	mg	945164	40344.88365
				supplier	metallization	Aluminium (Al)	7429-90-5		0.047	mg	6053	258.3758805
				supplier	metallization	Copper (Cu)	7440-50-8		0.141	mg	18037	769.9199995
				supplier	metallization	Nickel (Ni)	7440-02-0		0.001	mg	121	5.164956475
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.025	mg	3147	134.3315539
				supplier	metallization	Titanium (Ti)	7440-32-6		0.006	mg	726	30.98973885
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	121	5.164956475
				supplier	Passivation	Silicon Nitride	12033-89-5		0.034	mg	4358	186.0238043
				supplier	Passivation	Silicon Oxide	7631-86-9		0.175	mg	22273	950.7361617
				supplier	Organic Compounds	Acrylic resin	Proprietary		0.040	mg	60000	220.0484901
Glue Epoxy (EN4900GC)	Other Organic Materials	0.674	mg	supplier	Organic Compounds	Polybutadiene derivative	Proprietary		0.013	mg	20000	73.3494967
				supplier	Organic Compounds	Butadiene copolymer	Proprietary		0.010	mg	15000	55.01212252
				supplier	Organic Compounds	Acrylate	Proprietary		0.026	mg	39000	143.0315186
				supplier	Organic Compounds	Epoxy resin	Proprietary		0.013	mg	20000	73.3494967
				supplier	Organic Compounds	Peroxide	Proprietary		0.005	mg	8000	29.33979868
				supplier	Organic Compounds	Additive	Proprietary		0.012	mg	18000	66.01454703
				supplier	Metals	Silver	7440-22-4		0.552	mg	820000	3007.329364
				supplier	Organic Compounds	Epoxy resin	Proprietary		4.271	mg	50000	23248.1645
Encapsulation (EME-G631BQ-CJ)	Other Organic Materials	85.421	mg	supplier	Organic Compounds	Phenol Resin	Proprietary		4.271	mg	50000	23248.1645
				supplier	Organic Compounds	Silica, vitreous	60676-86-0		70.045	mg	820000	381269.8977
				supplier	Glass	Silicon dioxide	7631-86-9		4.698	mg	55000	25572.98095
				supplier	Glass	Aluminium hydroxide	21645-51-2		1.708	mg	20000	9299.265799
				supplier	Organic Compounds	Carbon black	1333-86-4		0.299	mg	3500	1627.371515
				supplier	Organic Compounds	Carbonate(2-)]hexadecahydro	11097-59-9		0.128	mg	1500	697.4449349
				supplier	Metals	Copper	7440-50-8		0.675	mg	965500	3673.434547
Bonding Wire (Cu)	Bonding Wire	0.699	mg	supplier	Metals	Palladium	7440-05-3		0.022	mg	31000	117.9455939
				supplier	Metals	Gold	7440-57-5		0.002	mg	3500	13.31643803
				supplier	Metals	Tin	7440-31-5		1.528	mg	1000000	8315.719554
Plating anode (Sn)	Other inorganic materials	1.528	mg	supplier	Metals	Copper	7440-50-8		83.831	mg	957500	456309.2912
				supplier	Metals	Magnesium	7439-95-4		0.131	mg	1500	714.8448426
Leadframe (C7025 + Ag)	Copper & its alloys	87.552	mg	supplier	Metals	Nickel	7440-02-0		2.609	mg	29800	14201.58421
				supplier	Metals	Silicon	7440-21-3		0.569	mg	6500	3097.660985
				supplier	Metals	Silver	7440-22-4		0.411	mg	4700	2239.847173